

100V N-Channel Enhancement Mode MOSFET**Description**

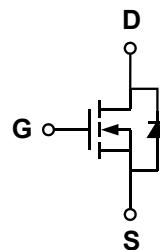
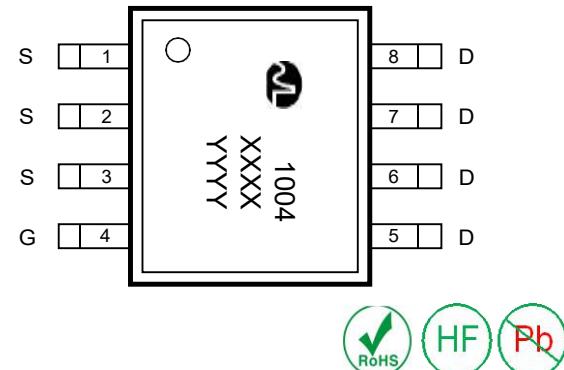
The PECN1004 uses trench MOSFET technology that is uniquely optimized to provide the most efficient high frequency switching performance. Conduction and switching losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and C_{rss} .

General Features

- ◆ $V_{DS} = 100V$ $I_D = 4A$
 $R_{DS(ON)}(\text{Typ.}) = 91m\Omega$ @ $V_{GS} = 10V$
 $R_{DS(ON)}(\text{Typ.}) = 110m\Omega$ @ $V_{GS} = 4.5V$
- ◆ Lead free product is acquired
- ◆ Surface mount package

Application

- ◆ High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- ◆ Networking DC-DC Power System
- ◆ Load switch

Package*100% UIS TESTED!**100% ΔV_{ds} TESTED!***Schematic diagram****Marking and pin assignment****SOP-8
(TOP VIEW)****Ordering Information**

Part Number	Storage Temperature	Package	Devices Per Reel
PECN1004S R	-55°C to +150°C	SOP-8	4000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V_{DS}	100	V
Gate-source voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	4	A
		3	
Pulsed Drain Current	I_{DP}	16	A
Avalanche energy(L=0.1mH)	EAS	14	mJ
Maximum power dissipation	P_D	2.5	W
Power Dissipation – Derate above 25°C		2	
Operating junction Temperature range	T_j	-55—150	°C

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	100	-	-	V
BVDSS Temperature Coefficient	△BV _{DSS} /△T _J	Reference to 25°C, ID=1mA		33		mV/°C
Zero gate voltage drain current	I _{DSS}	V _{DS} =100V, V _{GS} =0V	-	-	1	μA
		T _J =85°C	-	-	30	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.8	2.4	3.0	V
Drain-source on-state resistance ¹	R _{DS(ON)}	V _{GS} =10V, I _D =4A	-	91	120	mΩ
		V _{GS} =4.5V, I _D =3A		110	140	
On Status Drain Current	I _{D(ON)}	V _{DS} =5V, V _{GS} =4V	25	-	-	A
Diode Characteristics						
Diode Forward Voltage ¹	V _{SD}	I _{SD} =1A, V _{GS} =0V	-	0.8	1.1	V
Diode Continuous Forward Current	I _S		-	-	18	A
Reverse Recovery Time	t _{rr}	I _F =4A, dI/dt=100A/us	-	30	-	ns
Reverse Recovery Charge	Q _{rr}		-	44	-	nC
Dynamic Characteristics²						
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	3.3	-	Ω
Input capacitance	C _{iss}	V _{GS} =0V, V _{DS} =50V f=1.0MHz	-	556	-	pF
Output capacitance	C _{oss}		-	34.7	-	
Reverse transfer capacitance	C _{rss}		-	18.7	-	
Turn-on delay time	t _{D(ON)}	V _{DD} =50V, I _D =1A, V _{GS} =10V, R _{GEN} =6Ω	-	4.4	-	ns
Turn-on Rise time	t _r		-	21	-	
Turn-off delay time	t _{D(OFF)}		-	25	-	
Turn-off Fall time	t _f		-	21.2	-	
Total gate charge	Q _g	V _{GS} =10V, I _D =4A, V _{DS} =50V	-	20.5		nC
Gate-source charge	Q _{gs}		-	3.2		
Gate-drain charge	Q _{gd}		-	4	-	
Drain-Source Diode Characteristics						
Diode forward voltage	V _{SD}	ISD=4A, V _{GS} =0V	-	0.8	1.1	V

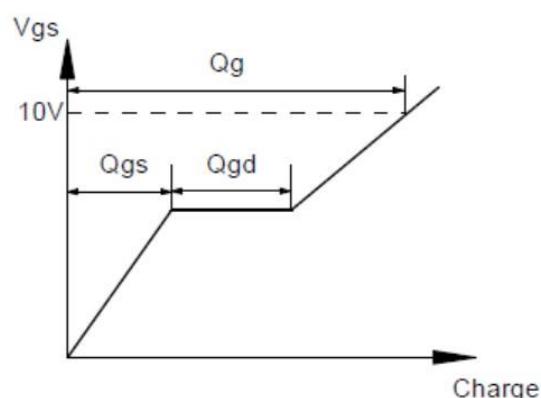
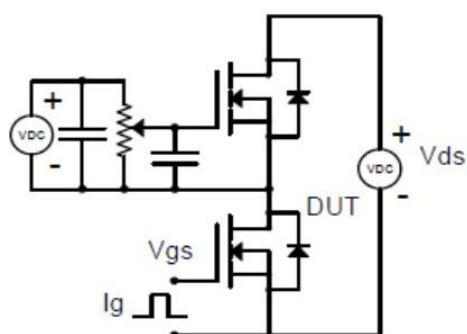
Note: 1: Pulse test; pulse width ≤ 300ns, duty cycle ≤ 2%.

2: Guaranteed by design, not subject to production testing.

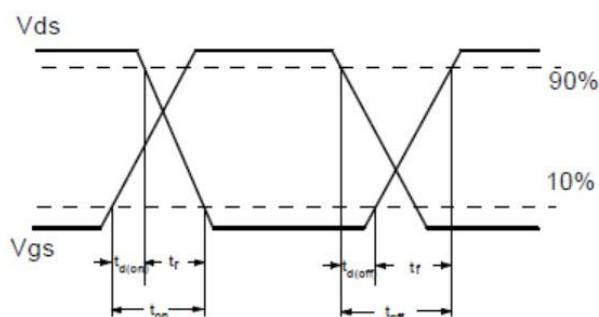
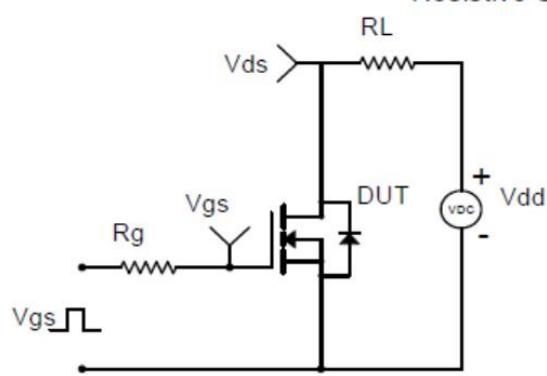
Thermal Characteristics

Parameter	Symbol	Typical	Unit
Thermal Resistance-Junction to Case	R _{θjc}	1.7	°C/W
Thermal Resistance junction-to ambient	R _{θja}	62.5	

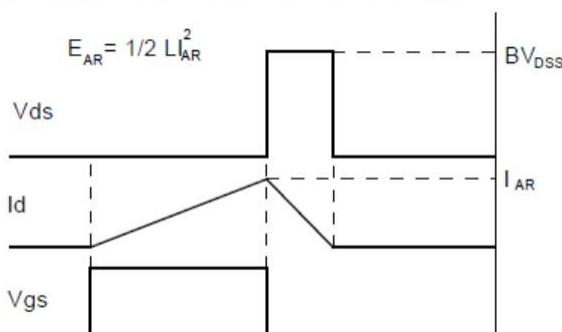
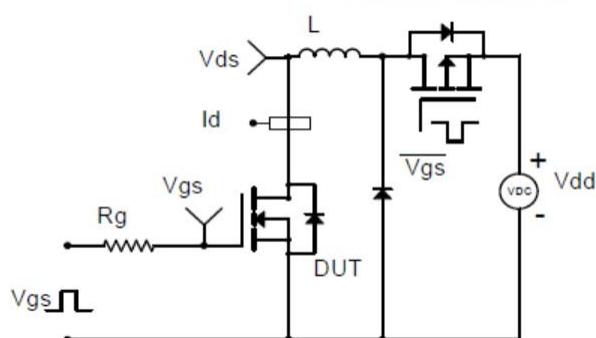
Gate Charge Test Circuit & Waveform



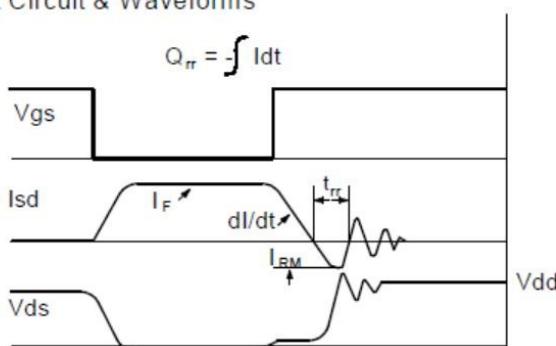
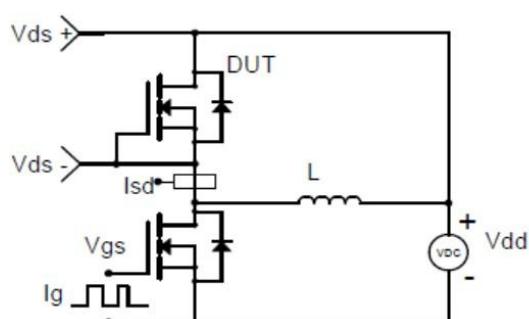
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

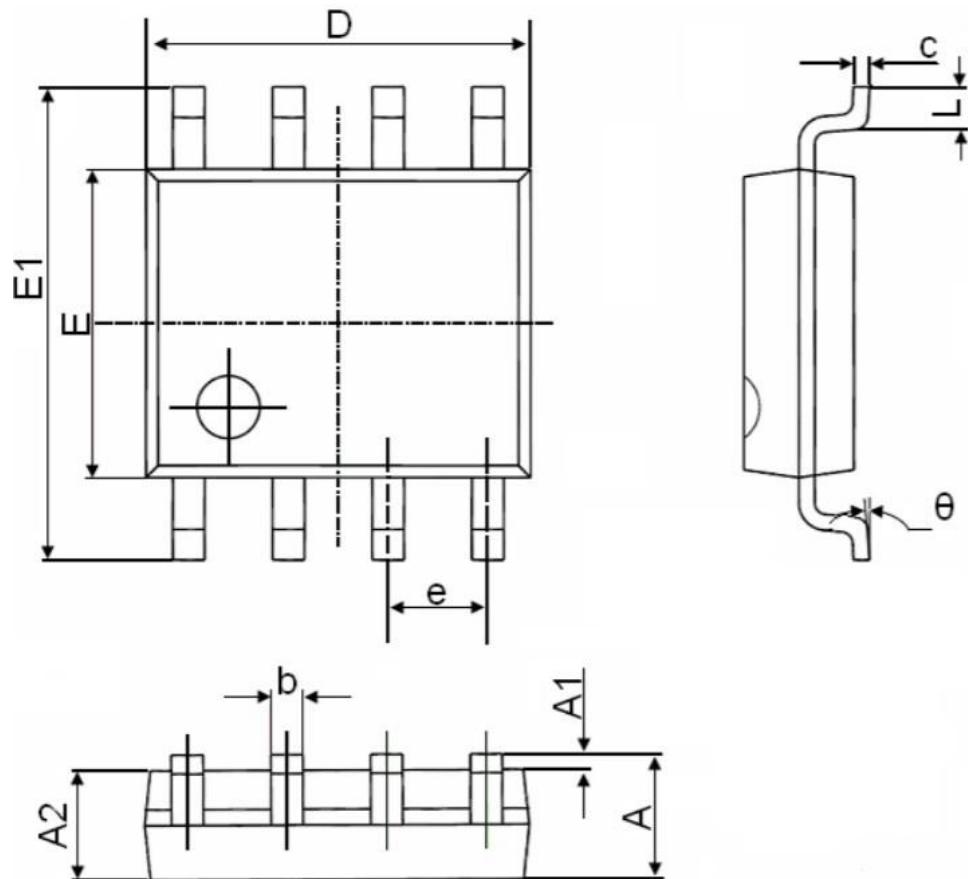


Diode Recovery Test Circuit & Waveforms



Package Information

- SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°